Hybrid 7p131 Traveler

May 30, 2000

1 Connectivity

Repairs on shorts:
Fixes for opens: B3B on chip 6 w/ wirebond.

2 Chips

The following chips were assembled on this hybrid (in the order that the chips get read out):
Hybrid 7P131 has die: 239-127 239-081 239-083 239-084 239-088 239-089 239-090

3 Data Analysis Summary

The following summarizes the findings of the Burn-in data analysis program. The first chip in the readout name is numbered 0.

```
% Hybrid 7p131 classification info. Created 10:46:33 05/29/00

Hybrid 7p131 quality: fair*
Chip classification: fair fair fair good good good fair*
Bad channels (chip-channel): 0-47 2-4 6-5 6-67 6-83
Bad cells: none
Random bad capacitors (chip-cell-channel): 1-29-20
Channels at pedestal needed for DCMS: 29.7 30.6 31.6 30.7 29.5 30.5 31.4
```

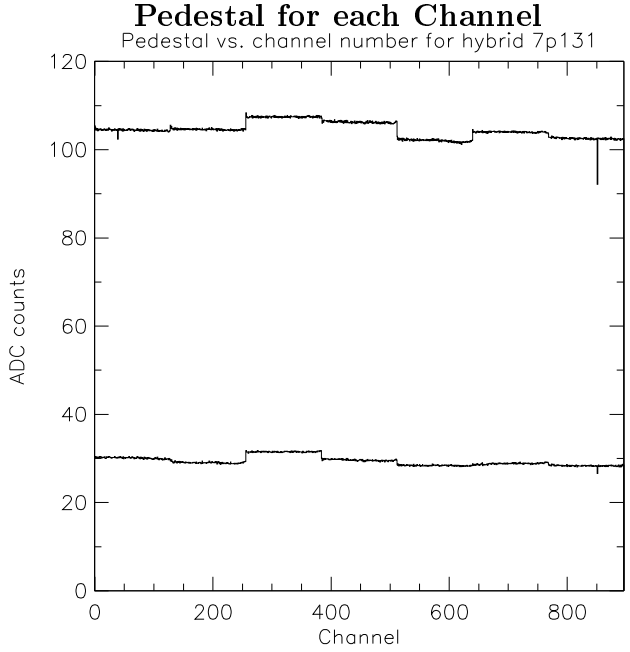
4 Comments

Encapsulated. FE DV finger gold bonds. HV tested.

5 Pedestal

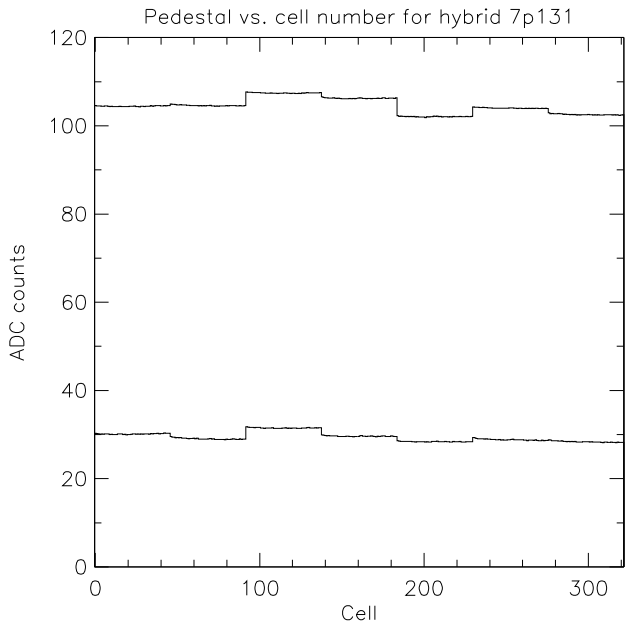
The following plot shows the pedestals vs. channel number with and without charge injection:

Pedestal for each Channel



The following plot shows the average pedestal vs. pipeline cell ID with and without charge injection. The x-axis is cell ID offset by 46 for each chip. Thus cell ID 5 for chip 1 is at x=5, chip 2 at x=51, chip 3 at x=97, etc.

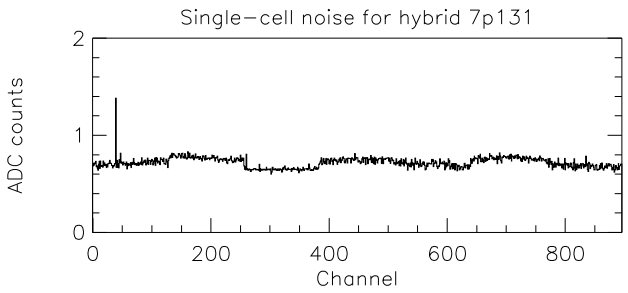
Pedestal vs. Pipeline Cell ID

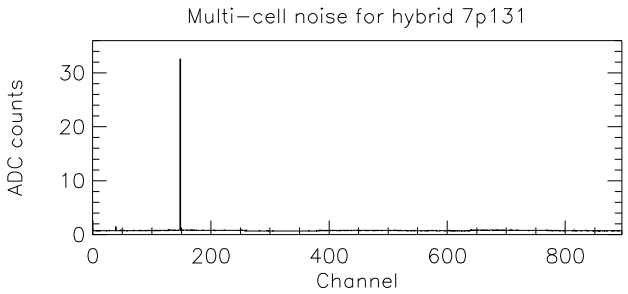


6 Noise

The following plots show the single-cell and multi-cell RMS noise:

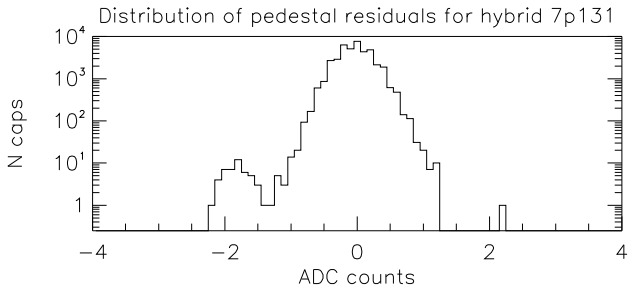
RMS Noise

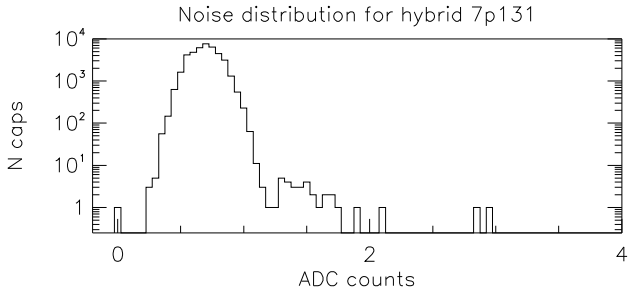




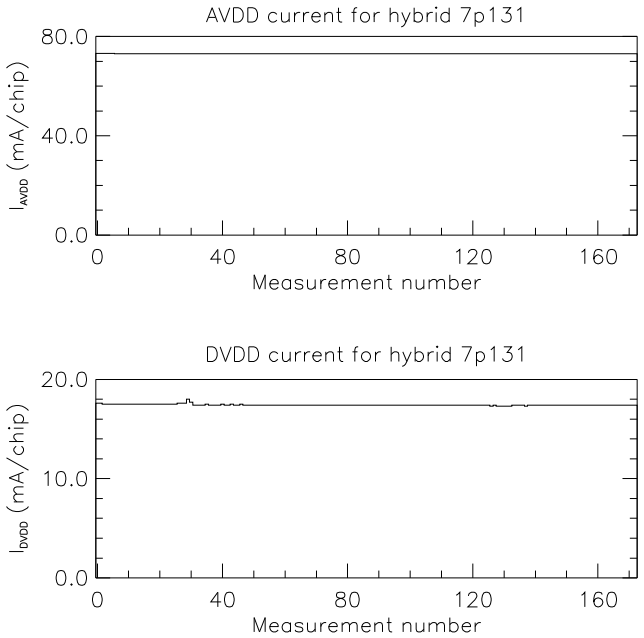
The following are histograms of the pedestal of each pipeline capacitor relative to the chip average (top); and the RMS noise of each capacitor (bottom):

Distribution of Pedestals and Noise





7 Currents

The following plots show the supply currents per chip as a function of measurment number. Currents are measured approximately every 10 minutes:

Supply Currents During Burn-in